#### C8/B.TECH/ECE(O)/ODD/SEM-7/EC-702/2019-20



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Paper Code: EC-702

PUID: 07076 (To be mentioned in the main answer script)

#### MICROELECTRONICS & VLSI DESIGN

Time Allotted: 3 Hours

Full Marks: 70

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The figures in the margin indicate full marks.

Candidates are required to give their answers in their own words as far as practicable.

#### GROUP - A

#### ( Multiple Choice Type Questions )

- 1. Choose the correct alternatives for any ten of the following:  $10 \times 1 = 10$ 
  - i) Frequency compensation for an op-amp can be achieved by
    - a increasing gain
    - b) minimizing overall phase shift
    - c) adding a zero
    - d) none of these.

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- ii) Slant in (ID-VDs) occurs due to
  - a) body effect
  - b) velocity saturation
  - (c) channel length modulation
  - d) mobility degradation.
- iii) Which is not a part of FPGA?
  - a) Configurable logic block
  - b) IOB
  - c) Microprocessor
  - d) Routing Channels.
- iv) Which are the simple PLDs?
  - a) CPLD

b) FPGA

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c) CBIC

- dy Pla.
- v) How many CMOS transistors are needed to implement XOR gates?
  - a) 7

b) 10

c) 8

- d) 9.
- vi) What is full form of VHDL?
  - Very high speed integrated circuit Hardware description language (HDL)
  - b) Vast HDL
  - c) Very simple HDL
  - d) Very high HDL.
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#### vii) What is ASIC?

- a) Application simplified IC
- b) Applied IC
- Application specific IC
- d) Authentic IC.

## viii) VLSI design flow is a

- a) cyclic process only
- b) parallel process
- ey sequential & cyclic process
- d) none of these.

#### ix) VHDL is a

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- ay multithreaded program
- b) language like C
- c) single user program
- d) multiuser program.
- x) The output of physical design is
  - a) circuit

- b) layout
- c) logical model
- d) RTL schematic.
- xi) Typical manufacturing defects in IC fabrication are
  - a) layer to layer shorts
  - b) discontinuous wires
  - c) missing or damaged vias
  - d) any one of these.

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#### **GROUP - B**

#### ( Short Answer Type Questions.)

Answer any three of the following.  $3 \times 5 = 15$ 

- 2. Draw layout of MOSFET.
- 3. Design NOR with CMOS logic.
- 4/ Dfine op-amp? Explain the characteristics of op-amp.
- Implement the following Boolean functions with TG logic:
  - a) Y = ab' + bc + c'a
  - b) F = ab' + a'bc
- 6. Proof that  $(W/L)_P = 2.5 (W/L)_N$ .

#### GROUP - C

## (Long Answer Type Questions)

Answer any three of the following.  $3 \times 15 = 45$ 

- What are the different types of ASIC? Explain briefly all of them.
- Explain the VTC curve of CMOS logic. Calculate the Vth of CMOS inverter.
- What do you mean by twin tub? Explain the p-well CMOS fabrication process with necessary diagram.

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- 10. Define Y chart. Explain it. What do you mean by regularity, locality, modularity. 3+3+3+3+3
- 11. Write short notes on any three of the following:  $3 \times 5$ 
  - 3) CMRR
  - (b) Domino logic
  - gy 6 transistor XOR design.
  - d) Edge triggered D slipslop.